

## Organizers:

VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM)

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In cooperation with:

UBC Microelectronics  
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## Venue: Hilton Hotel in Dresden



Dresden at the river Elbe

Cover picture: Courtesy of Toppan Photomasks

## The EMLC 2011 Program Committee:

Conference Chair: Dr. Uwe Behringer,  
UBC Microelectronics,  
Ammerbuch, Germany

Co-Conference Chair: Naoya Hayashi,  
DNP, Saitama, Japan

Chris Gale,  
Applied Materials,  
Dresden, Germany

Program Chairs: Rolf Seltmann, Globalfoundries,  
Dresden, Germany

Jacques Waelpoel,  
ASML, Veldhoven, Netherlands

Co-Program Chair: Warren Montgomery,  
CSNE assignee at SEMATECH,  
Albany, NY, USA

Dr. M. Arnz, Carl Zeiss SMT AG, Oberkochen, Germany  
Dr. C. Blaesing, Carl Zeiss SMS GmbH, Jena, Germany  
Mr. P Chen, Taiwan Mask Corp., Hsinchu, Taiwan  
Prof. R. Engelstad, University of Wisconsin, Madison, WI, USA  
Mr. C. Gale, Applied Materials, Dresden, Germany  
Mr. B. Grenon, Grenon Consulting, Inc., Colchester, VT, USA  
Mr. N. Hayashi, Dai Nippon Printing Co. Ltd., Saitama, Japan  
Dr. Greg Hughes, SEMATECH, Albany, NY, USA  
Mr. R. Jonckheere, IMEC, Leuven, Belgium  
Mr. W. Montgomery, SEMATECH, Albany, NY, USA  
Mrs. B. Lauche, Photronics MZD GmbH, Dresden, Germany  
Dr. H. Loeschner, IMS Nanofabrication AG, Vienna, Austria  
Mr. E. Rausa, Oerlikon USA Inc., Saint Petersburg, FL, USA  
Mr. D. J. Resnick, Molecular Imprints, Austin, TX, USA  
Dr. C. Romeo, Numonyx, Agrate Brianza, Italy  
Prof. H. Scheer, University of Wuppertal, Germany  
Dr. R. Schnabel, VDE/VDI-GMM, Frankfurt, Germany  
Dr. R. Seltmann, Globalfoundries, Dresden, Germany  
Mr. M. Staples, Globalfoundries, Dresden, Germany  
Mrs. I. Stolberg, Vistec Electron Beam GmbH, Jena, Germany  
Dr. S. Tedesco, CEA-LETI, Grenoble, France  
Dr. M. Tissier, Toppan Photomasks S.A., Rousset, France  
Mr. J. T. Weed, SYNOPSYS, Inc., Mountain View, CA, USA  
Mr. J. Whittey, KLA-Tencor, San Jose, USA  
Mr. H. Wolf, Photronics MZD GmbH, Dresden, Germany  
Dr. S. Wurm, SEMATECH, Albany, NY, USA  
Mr. L. Zurbrick, Agilent Technologies, Santa Clara, CA, USA

Please find the members of the **International Steering Committee** of the EMLC on the website:  
[www.emlc2011.com](http://www.emlc2011.com)

# GMM

VDE/VDI-GESELLSCHAFT  
MIKROELEKTRONIK, MIKROSYSTEM-  
UND FEINWERKTECHNIK



## Call for Papers

## The 27<sup>th</sup> European Mask and Lithography Conference EMLC 2011

January 18 – 19, 2011

Hilton Hotel

Dresden, Germany

[www.emlc2011.com](http://www.emlc2011.com)



The VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

**27<sup>th</sup> European Mask and Lithography Conference, EMLC 2011**  
**at the Hilton Hotel in Dresden, Germany**  
**January 18 - January 19, 2011**

The focus of this two-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

**Conference Schedule:**

The conference will start on Tuesday, January 18, 2011, at 09:00 AM with a Keynote Session. The conference will close on Wednesday, January 19, 2011, late afternoon. The Poster Session will be held on Tuesday evening followed by the Conference Banquet Dinner.

**Technical Exhibition:**

On Tuesday and Wednesday there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the enclosed registration form to the conference chairperson as soon as possible, since exhibition space is limited.

**Conference Chairperson and Exhibition Organization:**

Dr. Uwe Behringer,  
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D-72119 Ammerbuch, Germany  
Phone: +49-171-4553196,  
Fax: +49-7073-50216  
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**Abstract Information**

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including (figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

**[www.EMLC2011.com](http://www.EMLC2011.com)**

**There you will find a link to [myspie.org](http://myspie.org)**

**Deadline for Abstracts: September 30<sup>th</sup> 2010**

**By submitting an abstract you agree to**

- Present your work in person at the conference
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **October 15<sup>th</sup> 2010**; further manuscript format and layout instructions will be provided at that time.

**Manuscripts:**

Please submit the original of the manuscript a.s.a.p.

As to further information concerning the submission procedure, please have a look at our homepage, **[www.emlc2011.com](http://www.emlc2011.com)**

**Deadline for Manuscripts: November 30<sup>th</sup> 2010**

All manuscripts will be subject to a critical peer review before they are accepted for publication in the SPIE Digital Library.

Please note: Late submissions may not be published.

Information on the format of the manuscripts and further details is also provided at the conference web site:

**[www.emlc2011.com](http://www.emlc2011.com)**

**The conference manuscripts will be published by SPIE**

**Conference Topics:**

Presentations are solicited for the following and related topics:

**Mask Manufacturing:**

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

**Mask Business:**

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

**Lithography and Mask Application:**

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

**Emerging Mask and Lithography Technologies:**

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write / Maskless Technologies

**Mask and Lithography Equipment**